DECLARATION FOR NON-PROVISIONAL PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below at 201 et seq. beneath my name.

I believe I am the original, first and sole inventor if only one name is listed at 201 below, or an original, first and joint inventor if plural names are listed at 201 et seq. below, of the subject matter which is claimed and for which a patent is sought on the invention entitled in:

METHOD FOR REDUCING FREE SURFACE ROUGHNESS OF A SEMICONDUCTOR WAFER

and for which a patent applicat ⊠ is attached hereto and include	ion: des amendment(s) filed on			(it	^applicable)	
was filed in the United State	es on as Application No.	(declaration not accompanying application) with				
was filed as PCT internation	nal Application No.	on		and was amended		
under PCT Article 19 on	vii	(if applicable)				
				(g upplicus	,	
I hereby state that I have rev amended by any amendment re	iewed and understand the conto ferred to above.	ents of the above iden	tified applic	ation, inclu	ding the claims, as	
I acknowledge the duty to discl Regulations, § 1.56.	ose information known to me to	be material to patentab	ility as defin	ned in Title	37, Code of Federal	
inventor's certificate listed belo	benefits under Title 35, United Sow and have also identified below pplication on which priority is complete.	w any foreign application	l) of any for on for patent	eign applica or inventor	tion(s) for patent or	
EARLIEST FOREIGN AI	PPLICATION(S), IF ANY, FILE	ED PRIOR TO THE FIL	LING DATE	OF THE A	PPLICATION	
APPLICATION NUMBER	COUNTRY	DATE OF FIL (day, month, y		PRIORITY CLAIMED		
0108859	French	July 4, 200	01		□ NO	
				☐ YES	□ NO	
I hereby claim the benefit und below.	der Title 35, United States Cod	e, § 119(e) of any Uni	ted States p	provisional :	application(s) listed	
PROVISIONAL APPLICATION NUMBER		FILING DATE				
				•		
as the subject matter of each of provided by the first paragraph me which is material to patenta	or Title 35, United States Code, of the claims of this application is of Title 35, United States Code bility as defined in Title 37, Coccation and the national or PCT in	s not disclosed in the pre § 112, I acknowledge de of Federal Regulatio	ior United S the duty to ns, § 1.56 w	States applic disclose inf hich became	ation in the manner formation known to	
NON-PROVISIONAL	ON-PROVISIONAL STATUS					
APPLICATION NO.	FILING DATE	PATENTED	PENE		ABANDONED	
PCT/FR02/02341	July 4, 2002		X			

^{*} for use only when the application is assigned to a company, partnership or other organization.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

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